HU2109

3A, High Efficiency uPOL Module

FEATURES:

- High Density uPOL Module
- 3A Output Current
- Input Voltage Range from 4.5V to 16V
- Output Voltage Range from 0.6V to 5.0V
- 93% Peak Efficiency
- Enable / PGOOD Function
- Automatic Power Saving/PWM Mode
- Protections (OCP: Non-latching, OTP)
- Internal Soft Start
- Compact Size: 6mm*6mm*3.5mm(Max)
- Pb-free for RoHS compliant
- MSL 2, 250C Reflow

APPLICATIONS:

- Distributed Power Supply
- Server, Workstation, and Storage
- Networking and Datacom

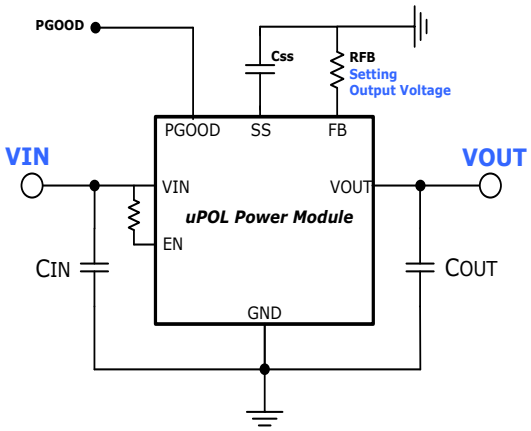
GENERAL DESCRIPTION:

The uPOL module is non-isolated dc-dc converters that can deliver up to 3A of output current. The PWM switching regulator, high frequency power inductor are integrated in one hybrid package. It only needs input/output capacitors and one voltage dividing resistor.

The module has automatic operation with PWM mode and power saving mode according to loading. Other features include remote enable function, internal soft-start, non-latching over current protection and power good.

The low profile and compact size package (6.0mm × 6.0mm x 3.5mm) is suitable for automated assembly by standard surface mount equipment. The uPOL module is Pb-free and RoHS compliance.

TYPICAL APPLICATION CIRCUIT & PACKAGE SIZE:



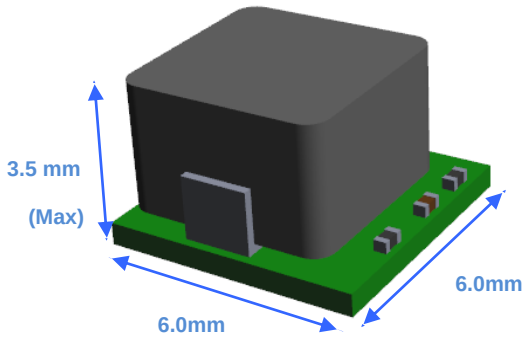


TABLE 1: OUTPUT VOLTAGE SETTING

Vout	1.0V	1.2V	1.8V	2.5V	3.3V	5.0V
RFB (Ohm)	150k	100k	49.9k	31.6k	22.1k	13.7k

HU2109

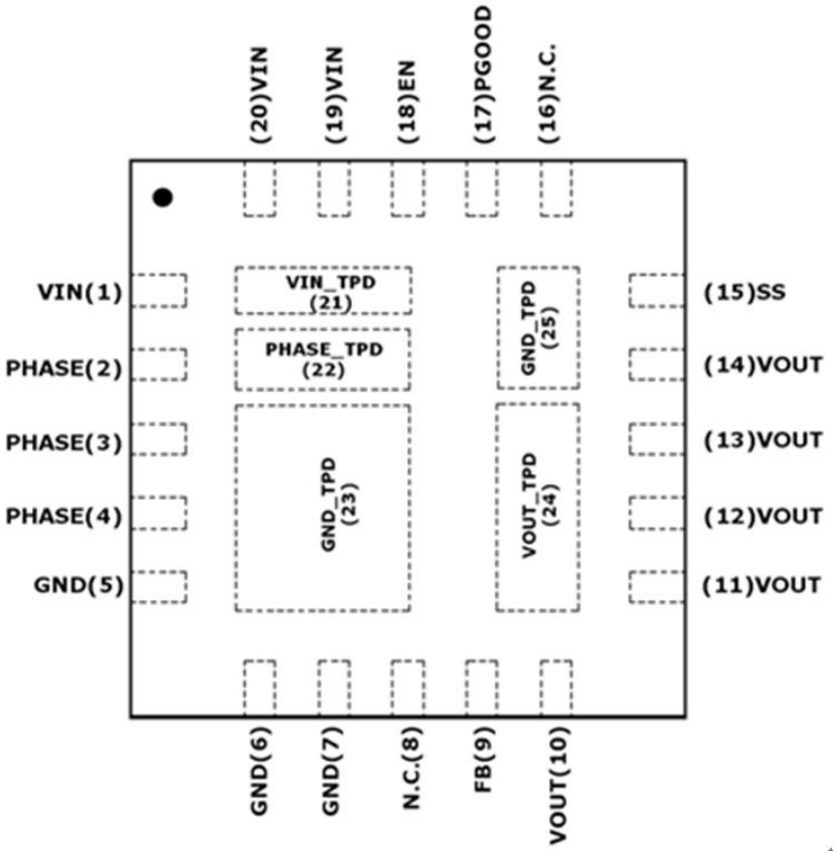
3A, High Efficiency uPOL Module

ORDER INFORMATION:

Part Number	Ambient Temp. Range (°C)	Package (Pb-Free)	MSL	Note
HU2109	-40 ~ +85	LGA	Level 2	-

Order Code	Packing	Quantity
HU2109	Tape and reel	1000

PIN CONFIGURATION:



TOP VIEW

HU2109

3A, High Efficiency uPOL Module

PIN DESCRIPTION:

Symbol	Pin No.	Description
VIN	1, 19, 20	Power input pin. It needs to connect input rail and thermal exposed pad of VIN_TPD(21) for heat transferring. Place the input ceramic type capacitor as closely as possible to this pin. One capacitor of 22uF at least for input capacitance.
PHASE	2, 3, 4	Switch output. Connect to thermal exposed pad of PHASE_TPD(22) for heat transferring.
GND	5, 6, 7	Power ground pin for signal, input, and output return path. This pin needs to connect one or more ground plane directly. Connect to thermal exposed pad of GND_TPD(23, 25) for heat transferring.
FB	9	Feedback input. Connect an external resistor divider from the FB to GND to set the output voltage.
VOUT	10, 11, 12, 13, 14	Power output pin. Connect to output and thermal exposed pad of VOUT_TPD(24) for heat transferring. Place the output capacitors as closely as possible to this pin. Two capacitors of 47uF at least for output capacitance.
SS	15	Soft start pin. It has internal current source for changing ramp up to set soft start time. Leave SS pin floating for default 1ms soft-start time.
N.C.	8,16	Not Connected.
PGOOD	17	Power good signal pin. Open drain output when the output voltage is above 90% of regulation point.
EN	18	On/Off control pin for module.
VIN_TPD	21	Power input pin. Connect input rail and using for heat transferring to heat dissipation layer by Vias connection.
PHASE_TPD	22	Phase node pin. Using for heat transferring to heat dissipation layer by Vias connection.
GND_TPD	23, 25	Power ground pin. It needs to connect one or more ground plane directly and using for heat transferring to heat dissipation layer by Vias connection.
VOUT_TPD	24	Power output pin. Connect to output and using for heat transferring to heat dissipation layer by Vias connection.

HU2109

3A, High Efficiency uPOL Module

ELECTRICAL SPECIFICATIONS:

CAUTION: Do not operate at or near absolute maximum rating listed for extended periods of time. This stress may adversely impact product reliability and result in failures not covered by warranty.

Parameter	Description	Min.	Typ.	Max.	Unit
■ Absolute Maximum Ratings					
VIN to GND		-	-	+18	V
VOUT to GND				+6.5	V
SW to GND	Note 1			VIN+0.3	V
EN to GND	Note 1	-	-	+6.0	V
Tc	Case Temperature of Inductor	-	-	+110	˚C
Tj	Junction Temperature	-40	-	+150	˚C
Tstg	Storage Temperature	-40	-	+125	˚C
■ Recommendation Operating Ratings					
VIN	Input Supply Voltage	+4.5	-	+16	V
VOUT	Adjusted Output Voltage	+0.6		+5.0	V
Ta	Ambient Temperature	-40	-	+85	˚C
■ Thermal Information					
Rth(j_{choke}-a)	Thermal resistance from junction to ambient (Note 2)	-	14	-	°C/W

NOTES:
1. Parameters guaranteed by power IC vendor design and test prior to module assembly.
2. Rth(j_{choke}-a) is measured with the component mounted on an effective thermal conductivity test board on 0 LFM condition. The test board size is 30mm×30mm×1.6mm with 4 layers. The test condition is complied with JEDEC EIJ/JESD 51 Standards.

HU2109

3A, High Efficiency uPOL Module

ELECTRICAL SPECIFICATIONS: (Cont.)

Conditions: T_A = 25 ºC, unless otherwise specified.
Vin = 12V, Vout = 5.0V, Cin = 22uF/16V/1206×2, Cout = 47uF/10V/1206×2.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
■ Input Characteristics						
$I_{SD(IN)}$	Input shutdown current	Vin =12V, EN = GND	-	5.5	-	uA
$I_{Q(IN)}$	Input supply bias current	Vin = 12V, Iout = 0A Vout = 5.0V, EN = VIN	-	0.13	-	mA
$I_{S(IN)}$	Input supply current	Vin = 12V, EN = VIN				
		Iout = 5mA,Vout =5.0V	-	2.5	-	mA
		Iout = 3A,Vout =5.0V	-	1.39	-	A
■ Output Characteristics						
$I_{OUT(DC)}$	Output continuous current range		0	-	3	A
$V_{O(SET)}$	Ouput Voltage Set Point	With 0.5% tolerance for external resistor used to set output voltage	-2.5		+2.5	% $V_{O(SET)}$
$\Delta V_{OUT}/\Delta V_{IN}$	Line regulation accuracy	Vin = 7.0V to 15V Vout = 5.0V, Iout = 0A Vout = 5.0V, Iout = 3A	-	0.2		% $V_{O(SET)}$
$\Delta V_{OUT}/\Delta I_{OUT}$	Load regulation accuracy	Iout = 0A to 3A Vin = 12V, Vout = 5.0V	-2		+3	% $V_{O(SET)}$
$V_{OUT(AC)}$	Output ripple voltage	Vin = 12V, Vout = 5.0V EN = VIN,20MHz Bandwidth	-	-	-	-
		IOUT = 5mA		25		mVp-p
		IOUT = 3A		30		mVp-p
■ Dynamic Characteristics						
ΔV_{OUT-DP}	Voltage change for positive load step	Iout = 0 A to 1.5A Current slew rate = 0.8A/uS Vin = 12V, Vout = 5V	-	35	-	mVp-p
ΔV_{OUT-DN}	Voltage change for negative load step	Iout = 1.5A to 0A Current slew rate = 0.8A/uS Vin = 12V, Vout = 5V	-	65	-	mVp-p
ΔV_{OUT-DP}	Voltage change for positive load step	Iout = 1.5 A to 3A Current slew rate = 0.8A/uS Vin = 12V, Vout = 5V	-	95	-	mVp-p
ΔV_{OUT-DN}	Voltage change for negative load step	Iout = 3A to 1.5A Current slew rate = 0.8A/uS Vin = 12V, Vout = 5V	-	85	-	mVp-p
■ Control Characteristics						
OCP	Protection Output Current	Note 3		4.1		A
F_{OSC}	Oscillator frequency	Note 3		1		MHz
V_{REF}	Referance voltage	Note 3	-1.5	0.600	+1.5	V/%
V_{PG}	Power good threshold	Note 3	88	90	92	% V_{REF}
$Toff_{MIN}$	Minimum Off time	Note 3	140	170	220	nS
Ton_{MIN}	Minimum On time	Note 3	50	80	120	nS

NOTES:
3. Parameters guaranteed by IC vendor design and test prior to module assembly.

HU2109

3A, High Efficiency uPOL Module

TYPICAL PERFORMANCE CHARACTERISTICS:

Conditions: T_A = 25 ºC, unless otherwise specified.
Cin = 22uF/16V/1206×2, Cout = 47uF/10V/1206×2.
Test Board Information: 30mm×30mm×1.6mm, 4 layers.

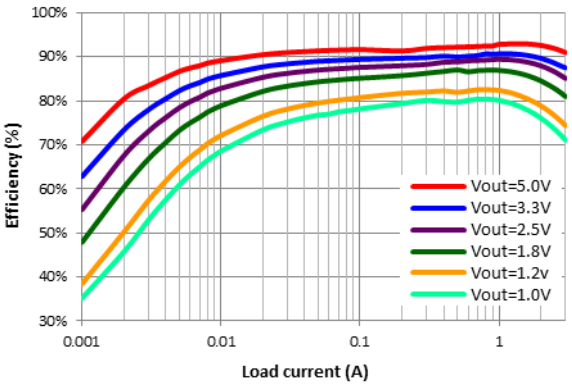


FIG.1 12VIN EFFICIENCY V.S. LOAD CURRENT

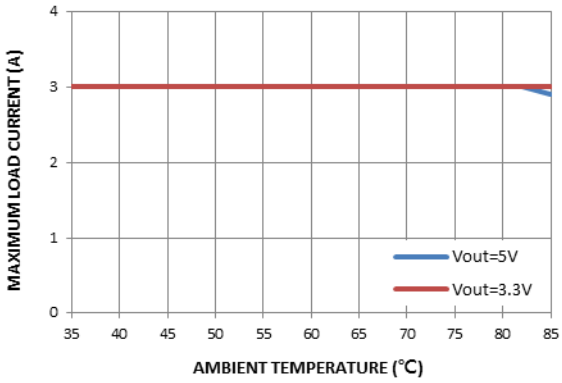


FIG.2 DE-RATING CURVE

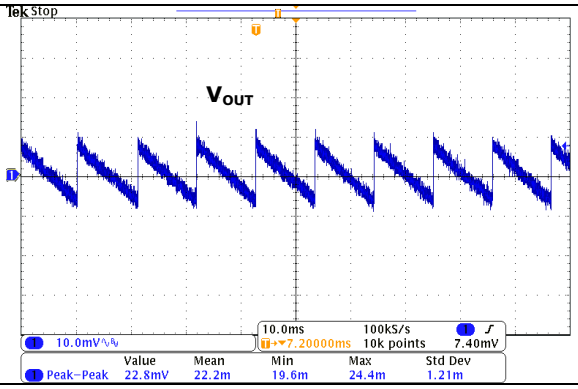


FIG.3 OUTPUT RIPPLE
(12VIN, 5VOUT, IOUT=0A)

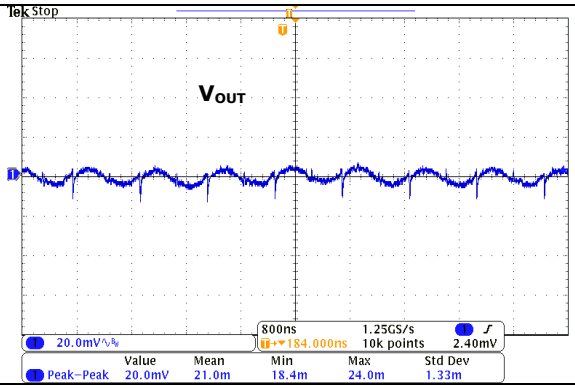


FIG.4 OUTPUT RIPPLE
(12VIN, 5VOUT, IOUT=3A)

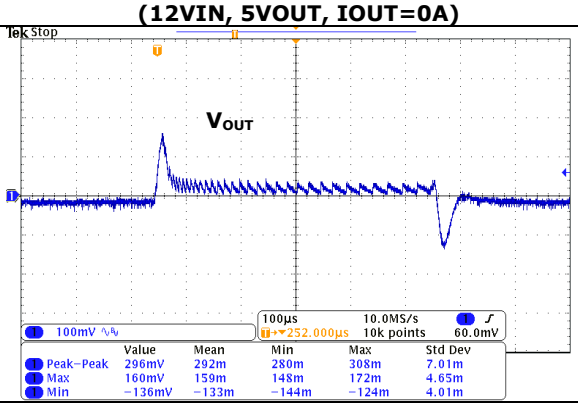


FIG.5 TRANSIENT RESPONSE
(12VIN, 5VOUT, 0% to 100% LOAD STEP)

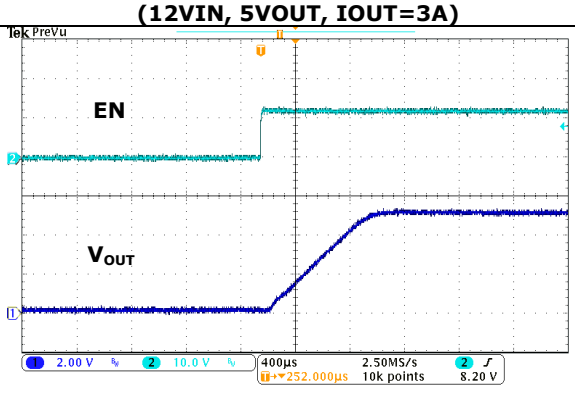


FIG.6 TURN-ON
(12VIN, 5VOUT, IOUT=3A)

HU2109

3A, High Efficiency uPOL Module

APPLICATIONS INFORMATION:

REFERENCE CIRCUIT FOR GENERAL APPLICATION:

The Figure 7 shows the HU2109 application schematics for input voltage +12V with automatic power saving function operation.

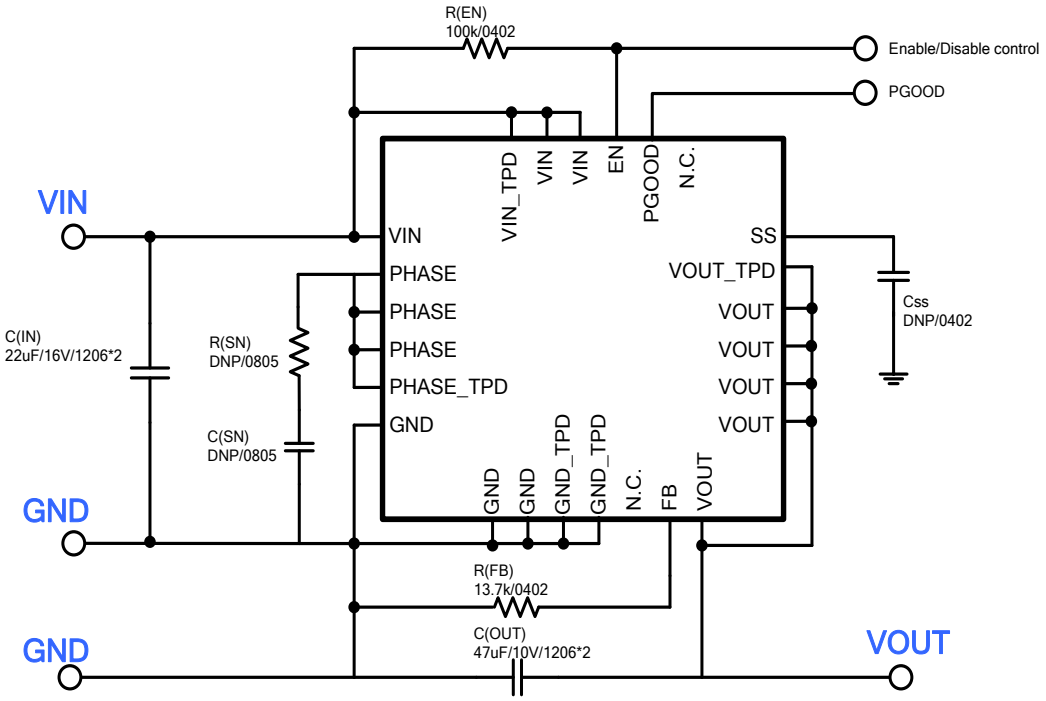


FIG.7 TYPICAL APPLICATION FOR PWM OPERATION

APPLICATIONS INFORMATION: (Cont.)

SAFETY CONSIDERATIONS:

Certain applications and/or safety agencies may require fuses at the inputs of power conversion components. Fuses should also be used when there is the possibility of sustained input voltage reversal which is not current limited. For greatest safety, we recommend a fast blow fuse installed in the ungrounded input supply line. The installer must observe all relevant safety standards and regulations.

For safety agency approvals, install the converter in compliance with the end-user safety standard.

INPUT FILTERING:

The module should be connected to as low AC impedance source supply and a highly inductive source or line inductance can affect the stability of the module. Input capacitors must be placed directly to the input pin of the module, to minimize input ripple voltage and ensure module stability.

OUTPUT FILTERING:

To reduce output ripple and improve the dynamic response to as step load change, the additional capacitors at the output must be used. Low ESR polymer and ceramic capacitors are recommended to improve the output ripple and dynamic response of the module.

PROGRAMMING OUTPUT VOLTAGE:

The module has an internal 0.6V±1.5% reference voltage. The output voltage can be programmed by the dividing resistance R_{FB} which respects to FB pin and GND pin. The output voltage can be calculated as shown in Equation 1 and the resistance according to typical output voltage is shown in TABLE 1.

$$\mathrm{VOUT\,(V)} = 0.6 \times \left(1 + \frac{100\mathrm{k}}{\mathrm{R_{FB}}}\right) \qquad \text{(EQ.1)}$$

PROGRAMMING SOFT-START:

Leave SS pin float for default 1ms soft-start time. This mechanism provides output voltage soft rise and no inrush current charges the output capacitors. The soft start time can be calculated as shown in Equation 2 for reference.

$$\mathrm{T_{SS}\,(Sec)} = \frac{\mathrm{C_{ss}} \times 0.6\mathrm{V}}{4\mathrm{uA}} \qquad \text{(EQ.2)}$$

APPLICATIONS INFORMATION: (Cont.)

RECOMMENDATION LAYOUT GUIDE:

In order to achieve stable, low losses, less noise or spike, and good thermal performance some layout considerations are necessary. The recommendation layout is shown as Figure 8.

1. The ground connection between pin 23, pin25 and pin 5 to 7 should be a solid ground plane under the module. It can be connected one or more ground plane by using several Vias.
2. Place high frequency ceramic capacitors between pin 1, pin 19 to 21 (VIN), and pin 23, pin25, pin 5 to 7 (GND) for input side; and pin 24, pin 10 to 14 (VOUT), and pin 23, pin25, pin 5 to 7 (GND) for output side, as close to module as possible to minimize high frequency noise.
3. Keep the R_{FB} connection trace to the module pin 9 (FB) short.
4. Use large copper area for power path (VIN, VOUT, and GND) to minimize the conduction loss and enhance heat transferring. Also, use multiple Vias to connect power planes in different layer.
5. Avoid any sensitive signal traces near the pin 24, and pin 2 to 4 (PHASE).

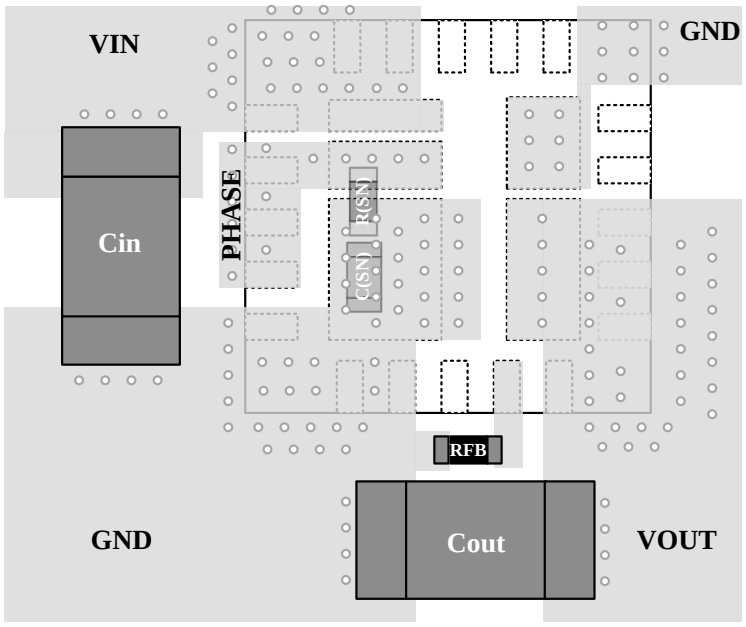


FIG.8 RECOMMENDATION LAYOUT (TOP LAYER)

APPLICATIONS INFORMATION: (Cont.)

Thermal Considerations:

All of thermal testing condition is complied with JEDEC EIJ/JESD 51 Standards. Therefore, the test board size is 30mm×30mm×1.6mm with 4 layers. The case temperature of module sensing point is shown as Figure 9. Then $Rth(j_{choke}\text{-}a)$ is measured with the component mounted on an effective thermal conductivity test board on 0 LFM condition. The HU2109 module is designed for using when the case temperature is below 110°C regardless the change of output current, input/output voltage or ambient temperature.

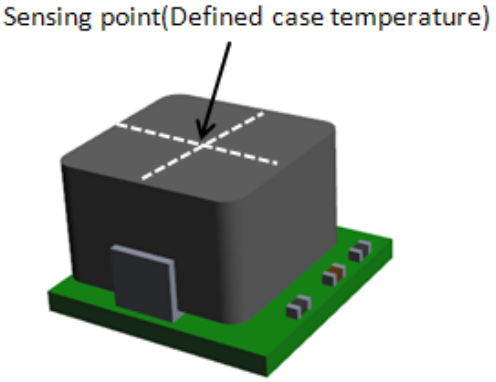


Figure 9 Case Temperature Sensing Point

REFLOW PARAMETERS:

Lead-free soldering process is a standard of making electronic products. Many solder alloys like Sn/Ag, Sn/Ag/Cu, Sn/Ag/Bi and so on are used extensively to replace traditional Sn/Pb alloy. Here the Sn/Ag/Cu alloy (SAC) are recommended for process. In the SAC alloy series, SAC305 is a very popular solder alloy which contains 3% Ag and 0.5% Cu. It is easy to get it. Figure 10 shows an example of reflow profile diagram. Typically, the profile has three stages. During the initial stage from 70°C to 90°C, the ramp rate of temperature should be not more than 1.5°C/sec. The soak zone then occurs from 100°C to 180°C and should last for 90 to 120 seconds. Finally the temperature rises to 230°C to 245°C and cover 220°C in 30 seconds to melt the solder. It is noted that the time of peak temperature should depend on the mass of the PCB board. The reflow profile is usually supported by the solder vendor and user could switch to optimize the profile according to various solder type and various manufactures' formula.

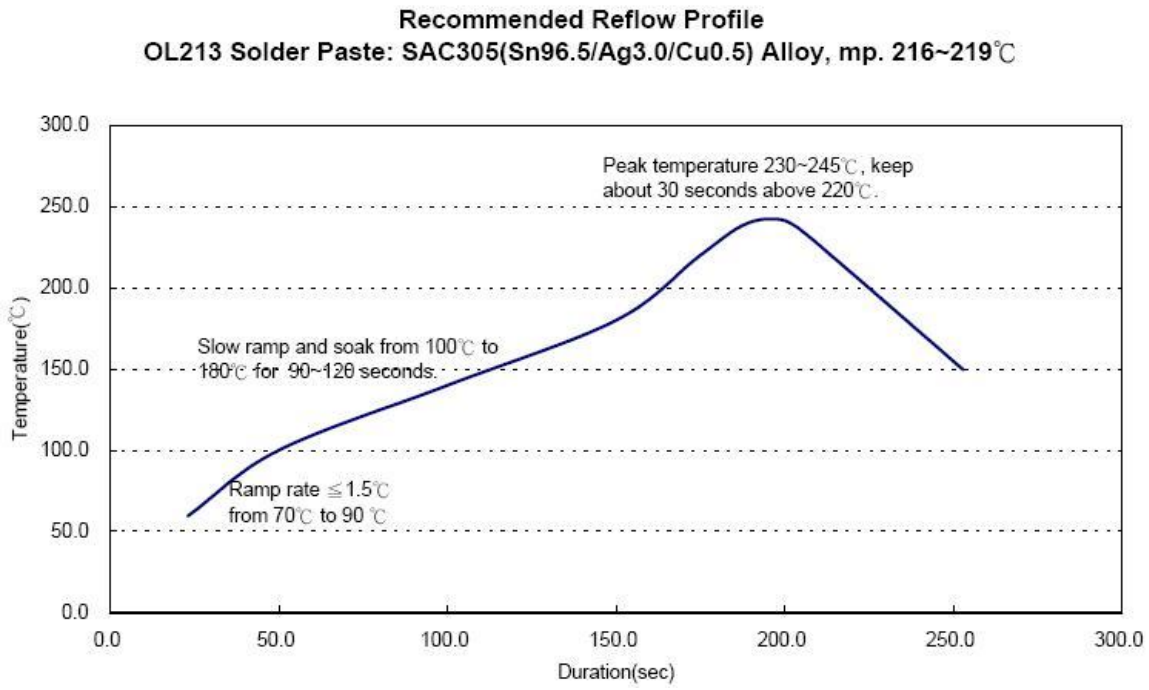


FIG.10 Recommendation Reflow Profile

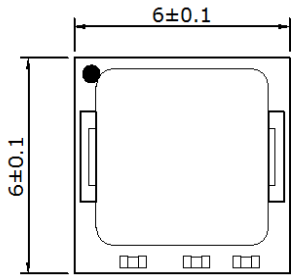
HU2109

3A, High Efficiency uPOL Module

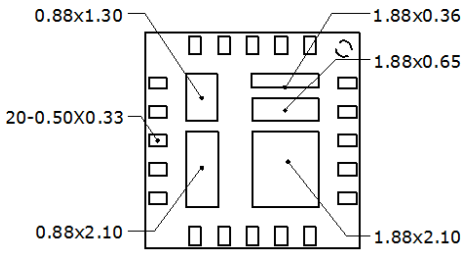
PACKAGE OUTLINE DRAWING:

unit: mm

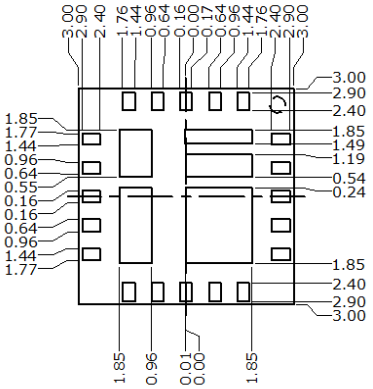
General Tolerance: ±0.1mm



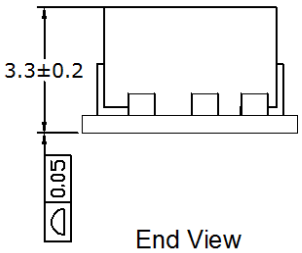
Top View



Bottom View



Bottom View



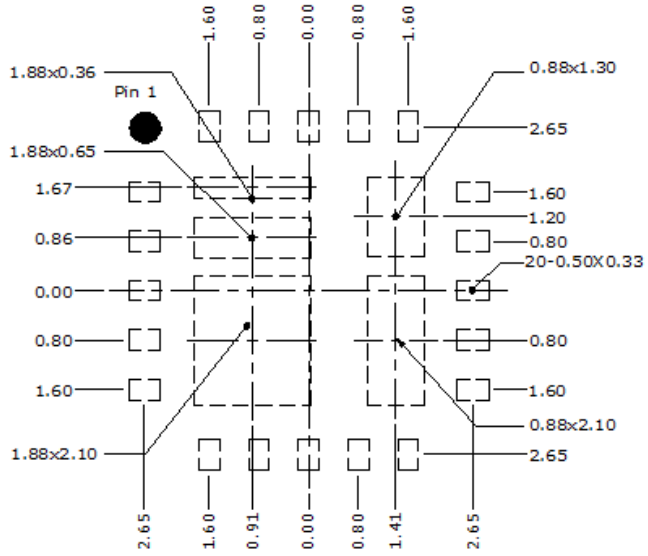
End View

HU2109

3A, High Efficiency uPOL Module

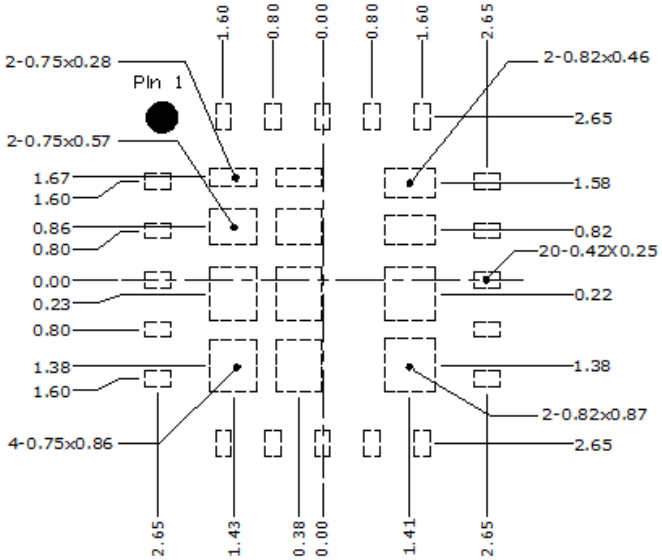
LAND PATTERN REFERENCE:

Unit:mm



Top View

TYPICAL RECOMMENDED LAND PATTERN



Top View

STENCIL PATTERN WITH SQUARE PADS

BASED ON 130um THICK STENCIL

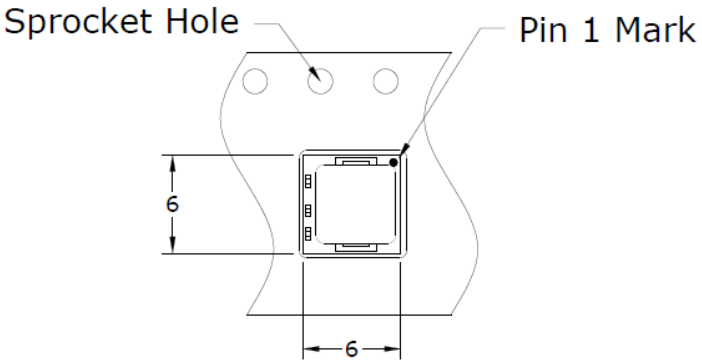
HU2109

3A, High Efficiency uPOL Module

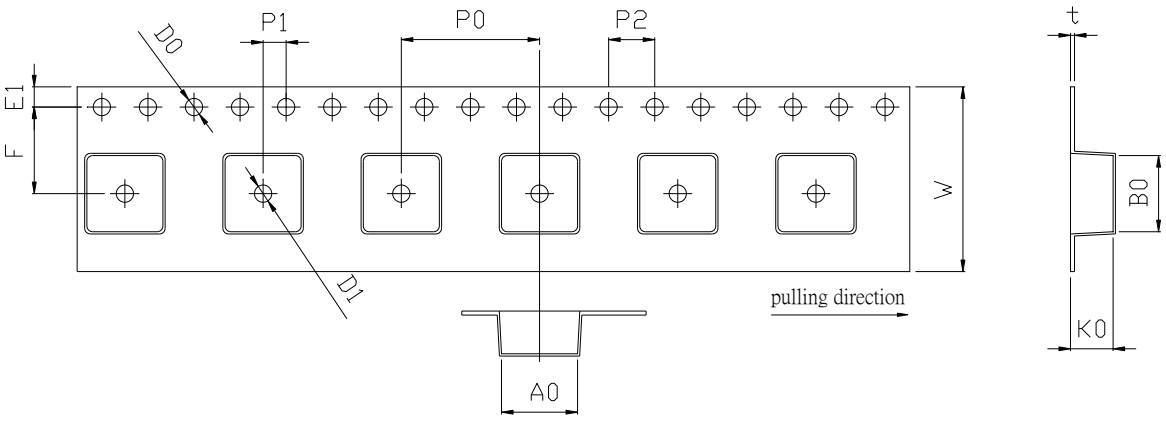
PACKING REFERENCE:

Unit: mm

Package In Tape Loading Orientation



Tape Dimension

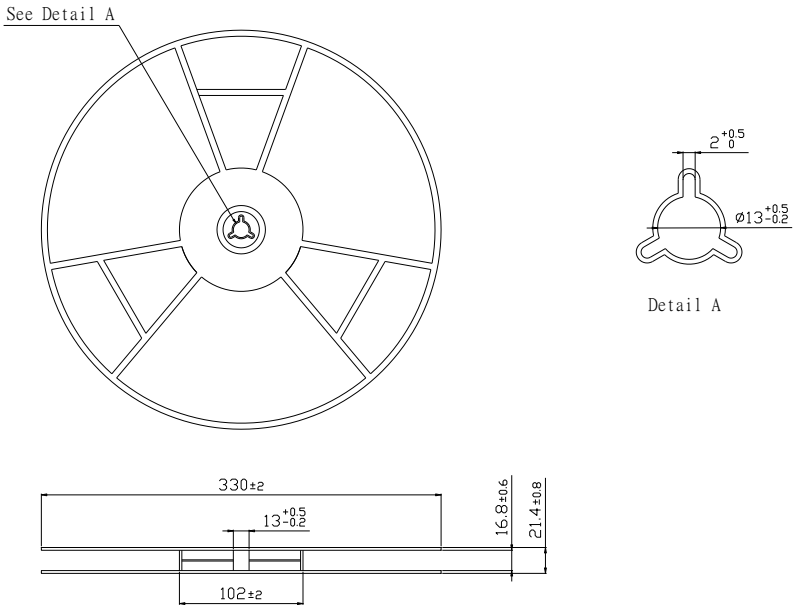


A0	6.60 ± 0.10	E1	1.75 ± 0.10
B0	6.60 ± 0.10	K0	3.70 ± 0.10
F	7.50 ± 0.10	P0	12.00 ± 0.10
W	16.00 ± 0.30	P1	2.00 ± 0.10
D0	φ1.5 +0.1/-0.0	P2	4.00 ± 0.10
D1	φ1.5 Min.	t	0.35 ± 0.05

PACKING REFERENCE: (Cont.)

Unit: mm

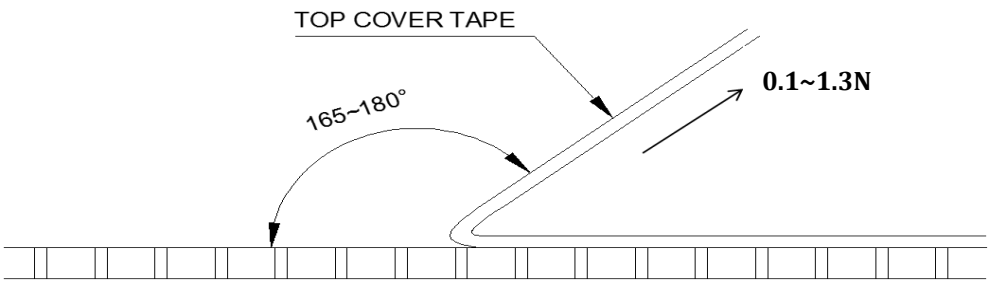
Reel Dimension



Peel Strength of Top Cover Tape

The peel speed shall be about 300mm/min.

The peel force of top cover tape shall between 0.1N to 1.3N



HU2109

3A, High Efficiency uPOL Module

REVERSION HISTORY:

Date	Revision	Changes
2014.11.20	00	Release the preliminary specification.
2014.12.18	01	Add packing and marking drawing.
2015.2.12	02	Change PIN 1 position: PIN CONFIGURATION, PACKAGE OUTLINE DRAWING, LAND PATTERN REFERENCE, PACKING REFERENCE
2015.02.26	03	1. Thermal Information: ● Delete Note 2 test board oz
2015.05.07	04	Change $I_{SD(IN)}$ and $I_{Q(IN)}$ current
2015.06.10	05	Change Recommendation Vout Operating Ratings
2015.06.24	06	Add REFLOW PARAMETERS